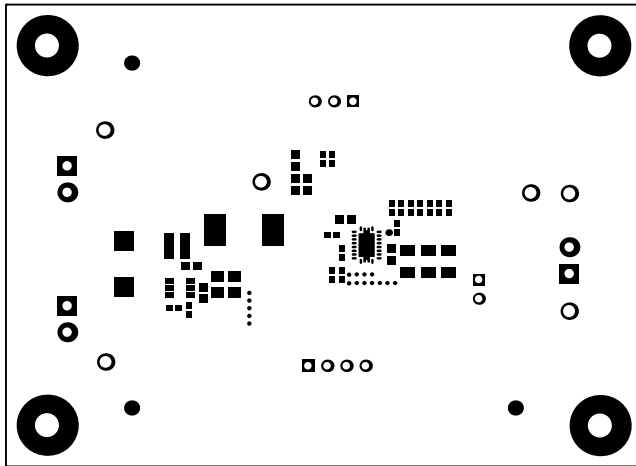
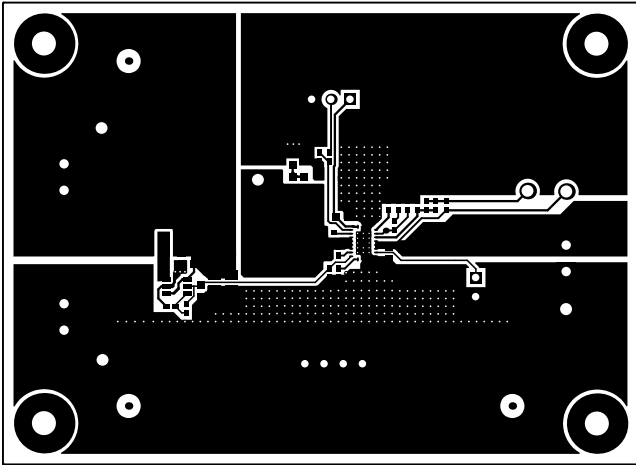


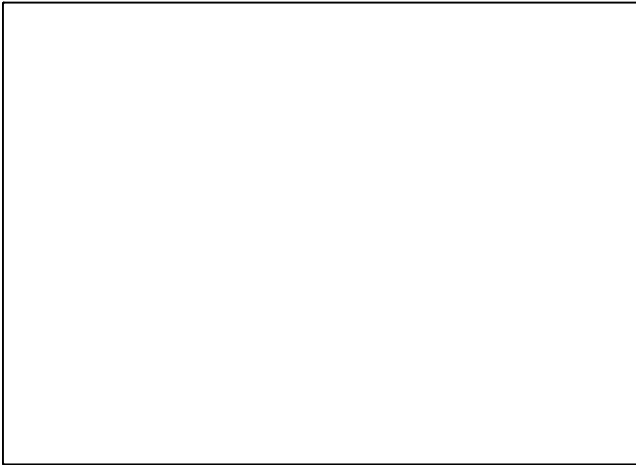
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9772	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 4/1/2015 3:41:07 PM	TEXAS INSTRUMENTS	



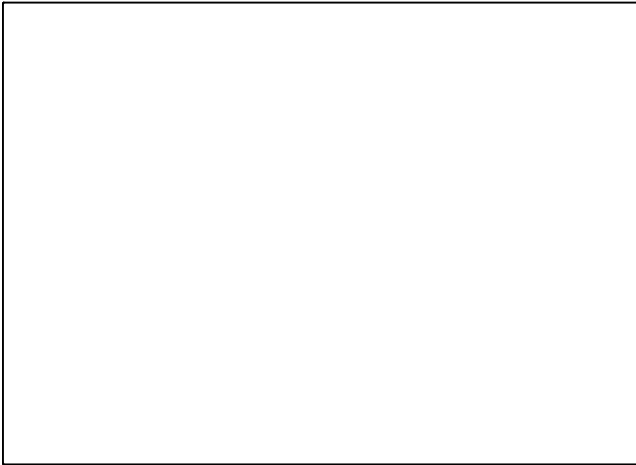
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8772	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 4/1/2015 3:41:08 PM	TEXAS INSTRUMENTS	



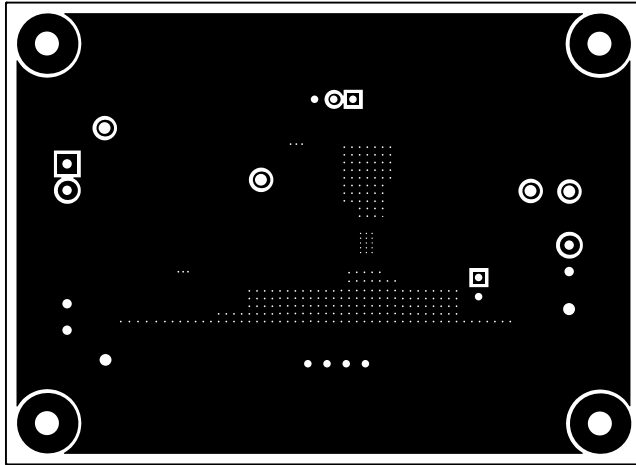
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8772	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 4/1/2015 3:41:09 PM	TEXAS INSTRUMENTS	



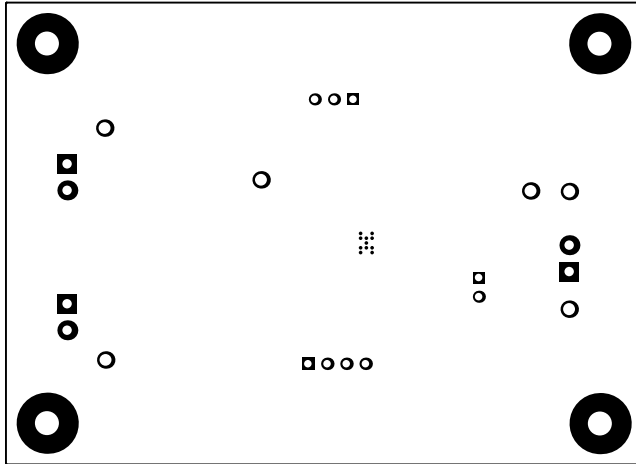
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8772	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = H1dLayer1	GENERATED : 4/1/2015 3:41:10 PM	TEXAS INSTRUMENTS	



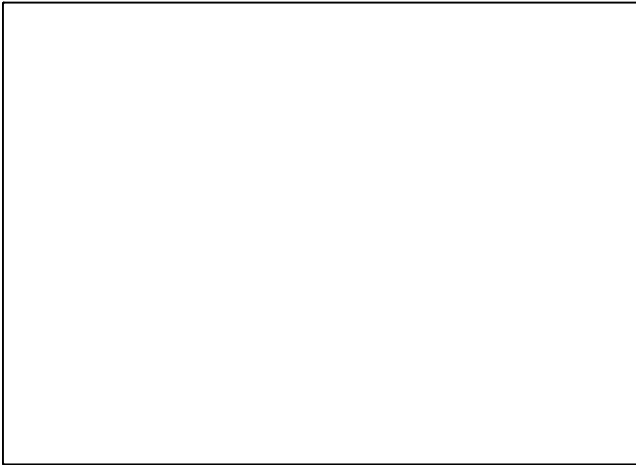
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8772	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = H1dLayer2	GENERATED : 4/1/2015 3:41:11 PM	TEXAS INSTRUMENTS	



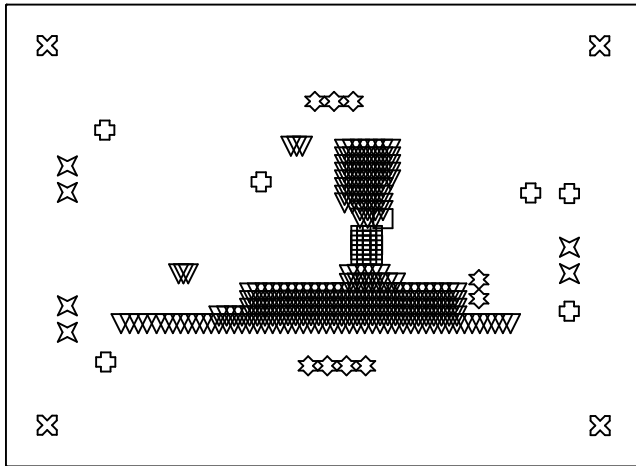
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8772	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 4/1/2015 3:41:12 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8772	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 4/1/2015 3:41:13 PM	TEXAS INSTRUMENTS	

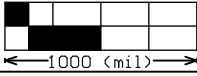


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8772	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 4/1/2015 3:41:14 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
⊗	4	125.98mil (3.200mm)	PTH	Round
⊗	6	50.00mil (1.270mm)	PTH	Round
⊗	6	63.00mil (1.600mm)	PTH	Round
⊗	9	40.00mil (1.016mm)	PTH	Round
□	16	7.87mil (0.200mm)	PTH	Round
▽	245	10.00mil (0.254mm)	PTH	Round
	286 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8772	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 4/1/2015 3:41:15 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8772	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 4/1/2015 3:41:16 PM	TEXAS INSTRUMENTS	

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